

IAP17 Rec'd PCT/PTO 27 DEC 2005

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A method of resin sealing of an electronic component ~~(2)~~ in a cavity ~~(16)~~ using an upper mold ~~(13)~~, a lower mold ~~(14)~~ opposite to said upper mold ~~(13)~~, a middle mold ~~(15)~~ provided between said upper mold ~~(13)~~ and said lower mold ~~(14)~~, and a release film ~~(17)~~ covering the cavity ~~(16)~~ of said lower mold ~~(14)~~; said method comprising the steps of:

attaching to said upper mold ~~(13)~~ an unsealed substrate ~~(4)~~ having said electronic component ~~(2)~~ mounted thereon;

covering a whole surface ~~(26, 54a, 54b)~~ of said cavity ~~(16)~~ with said release film ~~(17)~~ while said release film ~~(17)~~ is sandwiched between said lower mold ~~(14)~~ and said middle mold ~~(15)~~;

clamping said upper mold ~~(13)~~ together with said lower mold ~~(14)~~ and said middle mold ~~(15)~~ to immerse said electronic component ~~(2)~~ in a melting resin ~~(6)~~ in said cavity ~~(16)~~;

curing said melting resin ~~(6)~~ to form a cured resin ~~(10)~~;

opening said upper mold ~~(13)~~, said lower mold ~~(14)~~ and said middle mold ~~(15)~~; and

removing a sealed substrate ~~(11)~~ having said electronic component ~~(2)~~ enveloped in said cured resin ~~(10)~~ from said upper mold ~~(13)~~.

2. (Original) A mold used in the method of resin sealing of an electronic component according to claim 1.